

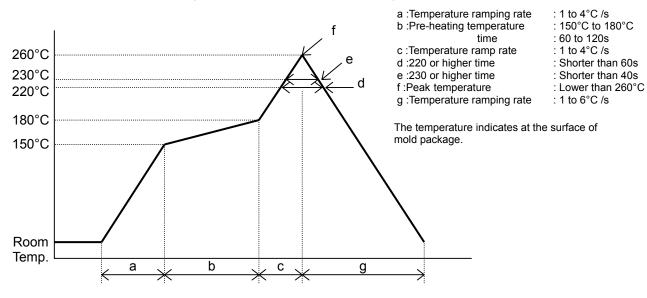
RECOMMENDED MOUNTING METHOD

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Soldering Methods, Recommended Soldering Method for Moisture-Proof Packing and Flux Cleaning are in the following. Mounting was evaluated with the following profiles in our company, so there was no problem. However, confirm mounting by the condition of your company beforehand.

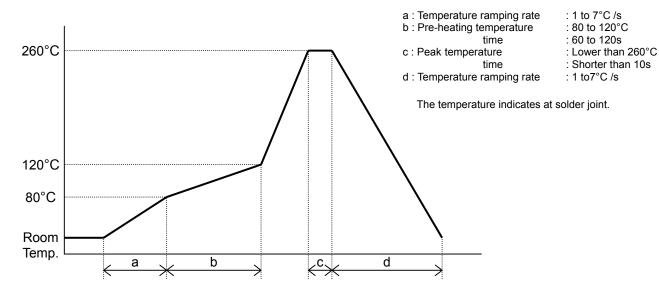
Soldering Temperature Profile of Reflow

Recommended reflow soldering temperature profile is in the following.



2. Soldering Temperature Profile of Flow

Recommended flow soldering temperature profile is in the following



3. Soldering Temperature Profile of Iron

Recommended iron soldering temperature profile is in the following.

At 1 lead Temperature : Lower than 350°C

Time : within 3s

4. Note

It is not good for IC's reliability to keep IC high temperature for long time within limit of recommended ranges. Please finish soldering as soon as possible within limit of recommended ranges.

See the next section, "IC storage Conditions and Duration" for Moisture-Proof Packing and Deaeration Packing.